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REVISIONS DOC. NO. SPC-F005 * Effective: 7/8/02 * DCP No: 1398 **DESCRIPTION** DRAWN DATE

CP # REV CHECKD DATE APPRVD DATE 2063 RELEASED 08/04/09 JWM 08/06/09 JWM 08/06/09 Α JN

SPC-F005.DWG

Pb-Free Assembly

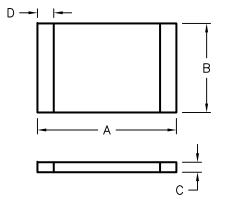
60-180 seconds

150°C

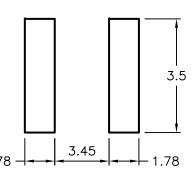
200°C

217°C

Dimension



Pad Layout



Solder reflow

- *Due to "Lead Free" nature, Temperature and Dwelling time for the soldering zone is higher than those for Regular. This may cause damage to other components.
- 1. Recommended max past thickness > 0.25mm.
- 2. Devices can be cleaned using standard methods and aqueous solvent.
- 3. Rework use standard industry practices.
- 4. Storage Envorinment: < 30°C / 60%RH

- 1. If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.
- 2. Devices are not designed to be wave soldered to the bottom side of the board.

SPECIFICATION



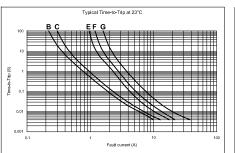
2. Soldering characteristic: Meets EIA specs. RS 186-9E,

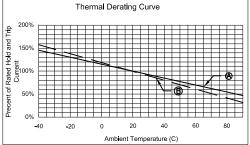
ANSI/J-std-002 Category 3

3. Operating Current: 100mA~2.0A

4. Maximum Voltage: 6V~60V

5. Temperature Range: -40°C to 85°C

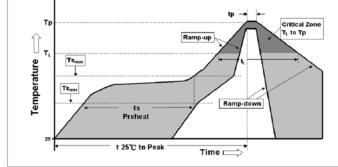




RoHS

Compliant

Reflow Profile



Time (tL)	60-150 seconds	
Peak/Classification Temperature(Tp):	260 C	
Time within 5°C of actual Peak:		
Temperature (tp)	20-40 seconds	

6 °C /second max. Ramp Down Rate: Time 25°C to Peak Temperature: 8 minutes max

Average Ramp-Up Rate (Tsmax to Tp) 3 C/second max.

	۸		Α		В	В		С.		c	C	С	D	Hold	Trlp	Rated	MaxImum	Typical	Max Tim	e-to-Trip	Resistance	Tolerance	Thermal Derating	Time-to-Trip												
Mfg. P/N		`	-					-																			•		Current	Current	Voltage	Current	Power	Current	Time	RMIN
	Min	Max	Min	Max	Min	Max	Min	IH, A	It, A	VMAX, Vdc	IMAX, A	Pd, W	Α	Sec	ohms	ohms	Curro opusii	Curve Opuon																		
MC33187	4.37	4.73	3.07	3.41	0.6	0.9	0.3	0.14	0.3	60	10	0.8	8	0.008	1.2	6.5	Option B	Option B																		
MC33188	4.37	4.73	3.07	3.41	0.6	0.9	0.3	0.2	0.4	30	10	0.8	8	0.02	0.8	5	Optlon B	Optlon C																		
MC33190	4.37	4.73	3.07	3.41	0.35	0.65	0.3	0.5	1	16	40	0.8	8	0.15	0.15	1	Optlon B	Option E																		
MC33193	4.37	4.73	3.07	3.41	0.35	0.65	0.3	0.75	1.5	16	40	0.8	8	0.2	0.11	0.45	Option A	Option F																		
MC33196	4.37	4.73	3.07	3.41	0.25	0.55	0.3	1.1	2.2	8	100	0.8	8	0.3	0.04	0.21	Optlon A	Option G																		

DISCLAIMER:

Profile Feature

Temperature Min (Tsmin)

Time (tsmin to tsmax)

Temperature(TL)

Temperature Max (Tsmax)

Time maintained above:

Preheat:

ALL STATEMENTS AND TECHNICAL INFORMATION CONTAINED HEREIN ARE BASED UPON INFORMATION AND/OR TESTS WE BELIEVE TO BE ACCURATE AND RELIABLE. SINCE CONDITIONS OF USE ARE BEYOND OUR CONTROL, THE USER SHALL DETERMINE THE SUITABILITY OF THE PRODUCT FOR THE INTENDED USE AND ASSUME ALL RISK AND LIABILITY WHATSOEVER IN CONNECTION THEREWITH.

TOLERANCES:

UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE FOR REFERENCE PURPOSES ONLY.

DRAWN BY:	DATE:
Jason Nash	08/06/09
CHECKED BY:	DATE:
JWM	08/06/09
APPROVED BY:	DATE:
JWM	08/06/09

DRAWING TITLE:

Surface Mountable PTC Resettable Fuse

ı	SIZE	DWG. NO.		ELEC	TRONIC FIL	E		RE\
	Α	Ta-	Ta-1192.dwg				Α	
	SCALE	E: NTS	U.O.M.: INCHES [mm]		SHEET:	1 0	F 1	1